## Chapter 17.24

## FEES/BONDS/DEPOSITS

Section:

17.24.010 Fees/Bonds/Deposits.

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Fees/bonds/deposits. Fees shall be assessed in accordance with the fee schedule adopted under the current Fees and Charges Resolution.

- A. Grading plan review fees. The applicant shall pay the plan review fee prior to acceptance of plans for checking by the City. If the earthwork quantities increase substantially or the plan changes substantially, additional fees may be charged for additional review required, as determined by the Public Works Director. Separate plan review fees shall also apply to retaining walls and major drainage structures.
- B. Grading permit fees. The applicant shall pay a grading permit fee prior to issuance of a grading permit by the City. Should the permitted grading work be revised and the scope of the work or quantity of earth moved be substantially changed, additional permit fees may be required for additional review required, as determined by the Public Works Director. Separate permits and fees shall apply to retaining walls or major drainage structures.
- C. Fees for unauthorized grading activity. Whenever grading operations are commenced which are not in conformance with or are without an approved grading permit, as required in Chapter 17.12, the applicable grading fee shall be treble the amount of the regular grading fee. The payment of such additional fee shall not exempt any person from compliance with the provisions of this grading ordinance nor from any other penalty prescribed by law (See Chapter 17.36).
- D. Bonds/developer's deposit. The Public Works Director may require bonds in such form and amounts as may be deemed necessary to assure that the work, if not completed on accordance with the approved plans and specifications, will be corrected to eliminate hazardous conditions. In lieu of a surety bond the applicant may file a cash bond or instrument of credit with the Public Works Director in an amount to that which would be required in the surety bond. (Ord. 6453 § 1, 1998)